

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| S1 | 22 | "205"/\$.ccls. and "204"/\$.ccls. and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5 plating) and ((tilt\$3 inclin\$3) near10 (substrate workpiece wafer)) and ((parallel) near15 anode) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/17 14:21 |
| S2 | 2 | "205"/\$.ccls. and "204"/\$.ccls. and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5 plating) and ((tilt\$3 inclin\$3) near10 (substrate workpiece wafer)) and ((parallel) near15 anode) and oscillat\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/17 15:03 |
| S3 | 13 | "205"/\$.ccls. and "204"/\$.ccls. and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5 plating) and ((tilt\$3 inclin\$3) near10 (substrate workpiece wafer)) and oscillat\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/17 15:04 |